

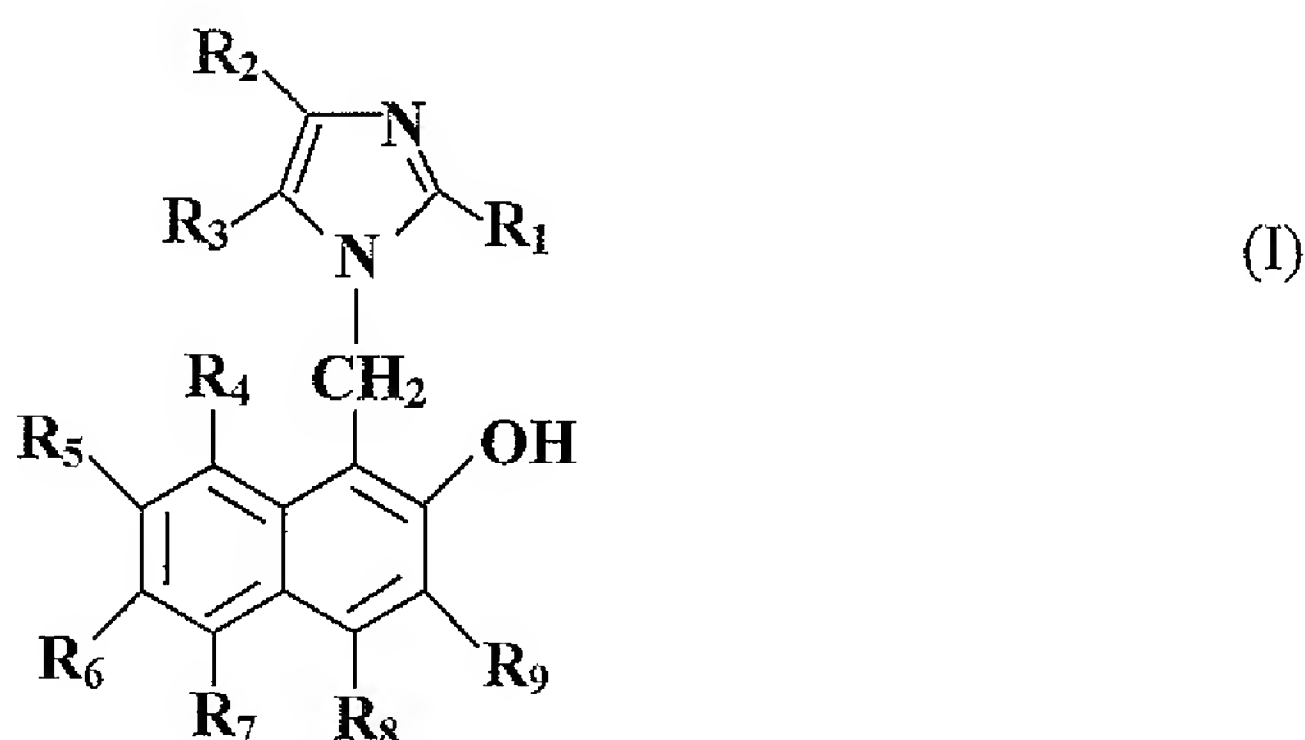
Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended). Composition comprising as component A) a 1-imidazolylmethyl-substituted 2-naphthol compound of the general formula (I)



where

R₁, R₂, and R₃ each independently of one another are H; C₁₋₁₇ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; or aromatic or aliphatic C₃₋₁₂ acyl;

R₄, R₅, R₆, R₇, R₈ and R₉ each independently of one another are H; C₁₋₁₂ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally

substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; C₁₋₁₂ alkoxy; or OH; and

as component B) a phenol selected from the group consisting of 1,4-n-pentylphenol, n-hexylphenol, n-heptylphenol, n-octylphenol, n-decylphenol, and O,O'-diallyl-bisphenol A which is liquid at room temperature, with a weight ratio of component A) to component B) being from 10:90 to 80:20.

Claim 2 (previously presented). Composition according to Claim 1, wherein R₁, R₂ and R₃ each independently of one another are H; C₁₋₁₂ alkyl; phenyl; or C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups.

Claim 3 (previously presented). Composition according to Claim 2, wherein R₂ and R₃ are each H; and R₁ is C₁₋₁₂ alkyl; phenyl; or C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups.

Claim 4 (previously presented). Composition according to Claim 3, wherein R_{2,3} are a hydrogen atom and R₁ is C₁₋₄ alkyl, or phenyl, optionally substituted by 1-3 C₁₋₄ alkyl groups.

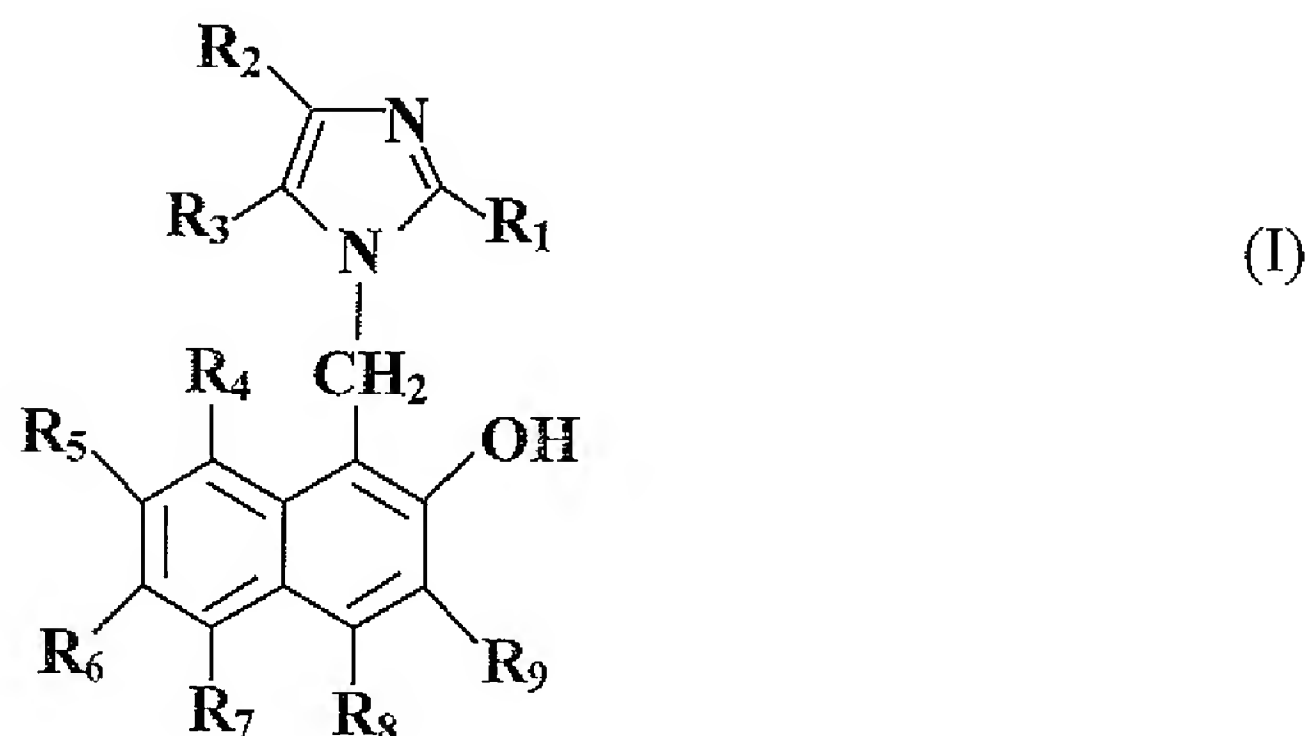
Claim 5 (currently amended). Composition according to Claim 1, wherein component B) is ~~1,4-n-pentyl, n-hexyl, n-heptyl, n-octyl, n-nonyl, n-decylphenol~~ or O,O'-diallyl-bisphenol A.

Claim 6 (previously presented). Composition according to Claim 1, characterized in that the weight ratio of component A) to component B) is from 20:80 to 70:30.

Claim 7 (cancelled).

Claim 8 (currently amended). Curable composition comprising:

- a) an epoxy resin whose epoxide content is from 0.1 to 11 epoxide equivalents/kg;
- b) from 5 to 40 parts by weight, based on the total weight of the curable composition, a composition comprising a 1-imidazolylmethyl-substituted 2-naphthol compound of the general formula (I)



where

R₁, R₂, and R₃ each independently of one another are H; C₁₋₁₇ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; or aromatic or aliphatic C₃₋₁₂ acyl;

R₄, R₅, R₆, R₇, R₈ and R₉ each independently of one another are H; C₁₋₁₂ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; C₁₋₁₂ alkoxy; or OH; and

a phenol selected from the group consisting of 1,4-n-pentylphenol, n-hexylphenol, n-heptylphenol, n-octylphenol, n-decylphenol, and O,O'-diallyl-bisphenol A

which is liquid at room temperature, the weight ratio of the 1-imidazolylmethyl-substituted 2-naphthol compound to phenol being from 10:90 to 80:20;

- c) a curing agent for the epoxy resin having from 0.5 to 1.5 functional groups per epoxide group; and optionally
- d) one or more additives.

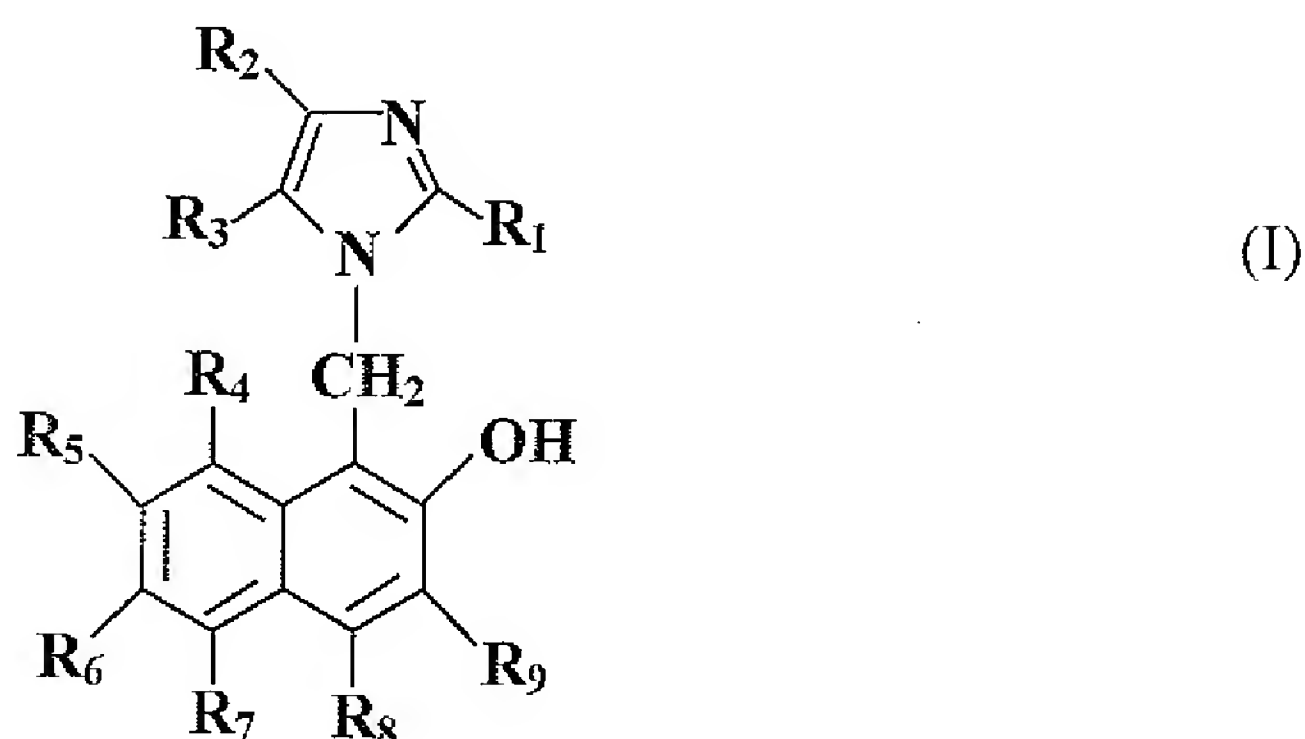
Claim 9 (previously presented). Composition according to Claim 8, wherein the curing agent is an amine or polyamine.

Claim 10 (previously presented). Composition according to Claim 9, characterized in that the curing agent is a polyoxypropylenediamine.

Claim 11 (original). Composition according to Claim 8, characterized in that the epoxy resin is a glycidyl ether, glycidyl ester, N-glycidyl or N,O-glycidyl derivative of an aromatic or heterocyclic compound, or a cycloaliphatic glycidyl compound.

Claim 12 (cancelled).

Claim 13 (currently amended). A method for making a curable composition comprising adding to an epoxy resin a curing agent, a 1-imidazolylmethyl-substituted 2-naphthol compound of the general formula (I)



where

R₁, R₂, and R₃ each independently of one another are H; C₁₋₁₇ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; or aromatic or aliphatic C₃₋₁₂ acyl;

R₄, R₅, R₆, R₇, R₈ and R₉ each independently of one another are H; C₁₋₁₂ alkyl; C₃₋₁₂ cycloalkyl, optionally substituted by C₁₋₄ alkyl groups; C₄₋₂₀ cycloalkyl-alkyl, optionally substituted by C₁₋₄ alkyl groups; C₆₋₁₀ aryl, optionally substituted by 1-3 C₁₋₄ alkyl

groups; C₇₋₁₅ phenylalkyl, optionally substituted by 1-3 C₁₋₄ alkyl groups; C₃₋₁₇ alkenyl; C₃₋₁₂ alkynyl; C₁₋₁₂ alkoxy; or OH; and

a phenol selected from the group consisting of 1,4-n-pentylphenol, n-hexylphenol, n-heptylphenol, n-octylphenol, n-decylphenol, and O,O'-diallyl-bisphenol A which is liquid at room temperature, the weight ratio of the 1-imidazolylmethyl-substituted 2-naphthol compound to phenol being from 10:90 to 80:20.

Claim 14 (previously presented). The method of claim 13 wherein the 1-imidazolylmethyl-substituted 2-naphthol compound of formula (I) and the phenol are dissolved beforehand in the curing agent at a temperature between 60° - 80° C.

Claim 15 (previously presented). A prepreg comprising a curable composition according to Claim 8.